



1753/ ZP.W

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Toshio NARITA et al.**

Group Art Unit: **1753**

Serial No.: **10/501,813**

Filed: **April 5, 2005**

Confirmation No.: **6606**

For: **METHOD FOR FORMING Re ALLOY COATING FILM HAVING  
HIGH Re CONTENT THROUGH ELECTROPLATING**

Attorney Docket Number: **042393**

Customer Number: **38834**

**REQUEST FOR CORRECTED FILING RECEIPT**

**Mail Stop: Missing Parts**

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

Date: May 16, 2005

Sir:

Please supply the undersigned attorney with a corrected filing receipt for the above-identified application. The undersigned also respectfully requests that the Patent and Trademark Office records be amended to reflect the correction.

In reviewing the Official Filing Receipt, we noted an error in the Title. The Title should read --METHOD FOR FORMING Re ALLOY COATING FILM HAVING HIGH Re CONTENT THROUGH ELECTROPLATING--. Also, we noted the Assignee's Information was not recorded. The Assignee's Information should read --JAPAN SCIENCE AND TECHNOLOGY AGENCY, Kawaguchi-shi, JAPAN; EBARA CORPORATION, Tokyo, JAPAN; SAPPORO ELECTROPLATING INDUSTRIAL CO., LTD., Sapporo-shi, JAPAN--. Copies of the PCT Publication and the Transmittal Letter is enclosed which

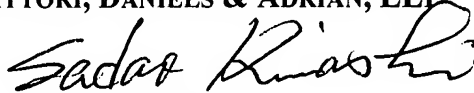
Request for Corrected Filing Receipt  
10/501,813  
042393

indicate the correct information. We are also enclosing a copy of the filing receipt with the corrections highlighted.

In the event any fees are required in connection with this paper, please charge Deposit Account No. 50-2866.

Respectfully submitted,

**WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP**

A handwritten signature in black ink, appearing to read "Sadao Kinashi", written in a cursive style.

Sadao Kinashi

Attorney for Applicants

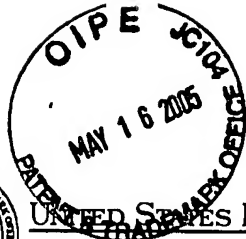
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SK/if

Enclosures: Official Filing Receipt; PCT publication; Transmittal Letter



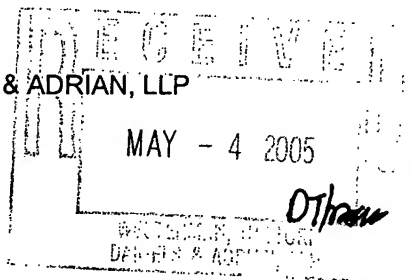
## UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/501,813	04/05/2005	1753	1470	042393	3	7	2

38834

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CONFIRMATION NO. 6606

## FILING RECEIPT



\*OC000000015881839\*

Date Mailed: 04/27/2005

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

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Assignment for Published Patent Application  
 :-- JAPAN SCIENCE AND TECHNOLOGY AGENCY, Kawaguchi-shi, JAPAN--:  
 :-- EBARA CORPORATION, Tokyo, JAPAN--:  
 :-- SAPPORO ELECTROPLATING INDUSTRIAL CO., LTD., Sapporo-shi, JAPAN--:

Please Insert ←

Power of Attorney: The patent practitioners associated with Customer Number 38834.

## Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP03/00354 01/17/2003

## Foreign Applications

JAPAN 2002-10665 01/18/2002  
 JAPAN 2002-10811 01/18/2002

Projected Publication Date: 08/04/2005

Non-Publication Request: No

Early Publication Request: No

**Title**Method for forming ~~re~~ alloy coating film having high ~~re~~ content through electroplating~~Re~~~~Re~~**Preliminary Class**

205

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Title 35, United States Code, Section 184  
Title 37, Code of Federal Regulations, 5.11 & 5.15**

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U.S. DEPARTMENT OF COMMERCE, PATENT AND TRADEMARK OFFICE

DATE: July 19, 2004

TRANSMITTAL LETTER TO THE UNITED STATES DESIGNATED/ELECTED OFFICE (DO/EO/US) CONCERNING A FILING UNDER 35 U.S.C. 371

U.S. APPLN. NO. (if known):

INTERNATIONAL APPLICATION NO.:  
PCT/JP03/00354

INTERNATIONAL FILING DATE:  
JANUARY 17, 2003

PRIORITY DATE CLAIMED:  
JANUARY 18, 2002

TITLE OF INVENTION: **METHOD FOR FORMING HIGH-Re-CONTENT ALLOY FILM THROUGH ELECTROPLATING PROCESS**

APPLICANT(S) FOR DO/EO/US: **Toshio NARITA, Shigenari HAYASHI, Takayuki YOSHIOKA, Hiroshi YAKUWA, Michiaki SOUMA and Michihisa FUKUMOTO**

Applicant hereby submits to the United States Designated/Elected Office (DO/EO/US) the following items and other information:

1. ☒ This is a **FIRST** submission of items concerning a filing under 35 U.S.C. 371.
2. ☐ This is a **SECOND** or **SUBSEQUENT** submission of items concerning a filing under 35 U.S.C. 371.
3. ☒ This is an express request to begin national examination procedures (35 USC 371(f)). The submission must include items (5), (6), (9) and (17) indicated below.
4. ☒ The US has been elected (Article 31).
5. ☒ A copy of the International Application as filed (35 U.S.C. 371(c)(2)):
  - a. ☐ is transmitted herewith (required only if not transmitted by the International Bureau).
  - b. ☒ has been transmitted by the International Bureau.
  - c. ☐ is not required, as the application was filed in the United States Receiving Office (RO/US)
6. ☒ An English language translation of the International Application as filed (35 U.S.C. 371(c)(2)).
  - a. ☒ is attached hereto.
  - b. ☐ has been previously submitted under 35 U.S.C. 154(d)(4).
7. ☒ Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371(c)(3))
  - a. ☐ are transmitted herewith (required only if not transmitted by the International Bureau).
  - b. ☐ have been transmitted by the International Bureau.
  - c. ☐ have not been made; however, the time limit for making such amendments has NOT expired.
  - d. ☒ have not been made and will not be made.
8. ☐ A translation of the amendments to the claims under PCT Article 19 (35 U.S.C. 371(c)(3)).
9. ☐ An oath or declaration of the inventor(s) (35 U.S.C. 371(c)(4)).
10. ☐ An English language translation of the annexes to the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371(c)(5)).

**ITEMS 11. TO 16. BELOW CONCERN OTHER DOCUMENT(S) OR INFORMATION INCLUDED:**

11. ☒ An Information Disclosure Statement under 37 CFR 1.97 and 1.98 together with the international search report, PTO-1449 and 4 references.
12. ☐ An assignment document for recording. A separate cover sheet in compliance with 37 CFR 3.28 and 3.31 is included. ASSIGNEES NAMES AND ADDRESSES: **(1) JAPAN SCIENCE AND TECHNOLOGY AGENCY, Kawaguchi-shi, (2) EBARA CORPORATION, Tokyo, Japan; and (3) SAPPORO ELECTROPLATING INDUSTRIAL CO., LTD., Sapporo-shi, Japan**  
Please publish the assignee data with the application.
13. ☐ **FIRST** preliminary amendment.
14. ☐ A substitute specification.
15. ☐ A change of power of attorney and/or address letter.
16. ☒ Other items or information: 3 sheets of drawings.

(19) 世界知的所有権機関  
国際事務局(43) 国際公開日  
2003年7月31日 (31.07.2003)

PCT

(10) 国際公開番号  
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- (22) 国際出願日: 2003年1月17日 (17.01.2003)
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特願2002-10665 2002年1月18日 (18.01.2002) JP  
特願2002-10811 2002年1月18日 (18.01.2002) JP

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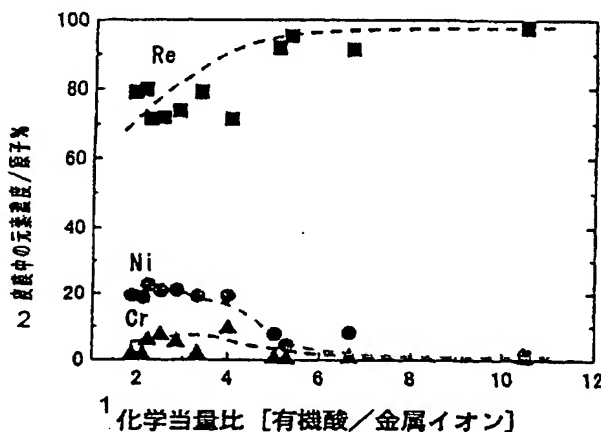
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(81) 指定国 (国内): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU,

[続葉有]

(54) Title: METHOD FOR FORMING Re ALLOY COATING FILM HAVING HIGH Re CONTENT THROUGH ELECTROPLATING

(54) 発明の名称: 電解めっきによる高濃度 Re 合金皮膜の形成方法



- 1...CHEMICAL EQUIVALENT RATIO [ORGANIC ACID/METAL ION]  
2...CONTENT OF ELEMENT IN COATING FILM/ATOMIC %

(57) Abstract: A method for forming a Re alloy coating film having a high Re content such as a Re coating film having a Re content of 98 atomic % or more, an alloy coating film containing Re in a content of  $65\% \leq \text{Re} < 98\%$  and at least one of Ni, Fe and Co, or the like, which comprises using an electroplating bath comprising an aqueous solution containing, a perrhenate ion, at least one of ions of Ni, Fe, Co, Cr and the like and further at least one selected from a Li ion and a Na ion. The formation of a Re alloy coating film having a high Re content being used as a corrosion-resistant alloy coating film for a member of a high temperature device through an electroplating using an aqueous solution has allowed the impartation of high heat resistance and corrosion resistance also to a member of a device having a complicated shape, with ease and at a low cost.

[続葉有]